2SB0949 (2SB949), 2SB0949A (2SB949A)

Silicon PNP epitaxial planar type darlington

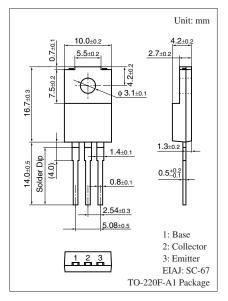
For power amplification and switching Complementary to 2SD1275 and 2SD1275A

Features

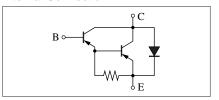
- High forward current transfer ratio h_{FE}
- High-speed switching
- Full-pack package which can be installed to the heat sink with one screw

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage	2SB0949	V _{CBO}	-60	V
(Emitter open)	2SB0949A		-80	
Collector-emitter voltage	2SB0949	V _{CEO}	-60	V
(Base open)	2SB0949A		-80	
Emitter-base voltage (Col	V _{EBO}	-5	V	
Collector current	I_C	-2	A	
Peak collector current	I_{CP}	-4	A	
Collector power	$T_C = 25^{\circ}C$	P _C	35	W
dissipation		2		
Junction temperature	T _j	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	



Internal Connection



■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

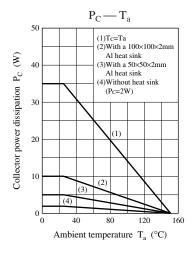
Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage	2SB0949	V _{CEO}	$I_C = -30 \text{ mA}, I_B = 0$	-60			V
(Base open)	2SB0949A			-80			
Base-emitter voltage		V_{BE}	$V_{CE} = -4 \text{ V}, I_{C} = -2 \text{ A}$			-2.8	V
Collector-base cutoff	2SB0949	I_{CBO}	$V_{CB} = -60 \text{ V}, I_E = 0$			-1	mA
current (Emitter open)	2SB0949A		$V_{CB} = -80 \text{ V}, I_E = 0$			-1	
Collector-emitter cutoff	2SB0949	I_{CEO}	$V_{CE} = -30 \text{ V}, I_B = 0$			-2	mA
current (Base open)	2SB0949A		$V_{CE} = -40 \text{ V}, I_{B} = 0$			-2	
Emitter-base cutoff current (Collector open)		I_{EBO}	$V_{EB} = -5 \text{ V}, I_C = 0$			-2	mA
Forward current transfer ratio		h _{FE1}	$V_{CE} = -4 \text{ V}, I_{C} = -1 \text{ A}$	1000			_
		h _{FE2} *	$V_{CE} = -4 \text{ V}, I_{C} = -2 \text{ A}$	1000		10 000	
Collector-emitter saturation	voltage	V _{CE(sat)}	$I_C = -2 \text{ A}, I_B = -8 \text{ mA}$			-2.5	V
Transition frequency		f_T	$V_{CE} = -10 \text{ V}, I_C = -0.5 \text{ A}, f = 1 \text{ MHz}$		20		MHz
Turn-on time		t _{on}	$I_C = -2 \text{ A}, I_{B1} = -8 \text{ mA}, I_{B2} = 8 \text{ mA}$		0.4		μs
Storage time		t _{stg}	$V_{CC} = -50 \text{ V}$		1.5		μs
Fall time		t_{f}			0.5		μs

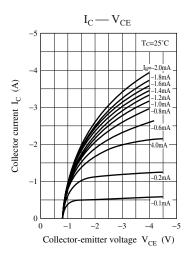
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

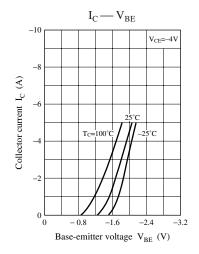
2. *: Rank classification

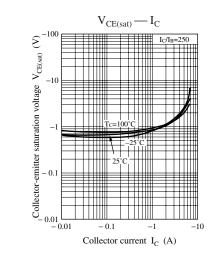
Rank	R	Q	Р	
h_{FE2}	1000 to 2500	2000 to 5000	4000 to 10000	

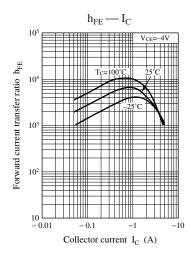
Note) The part numbers in the parenthesis show conventional part number.

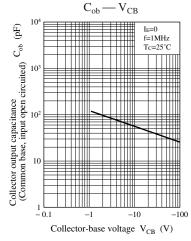


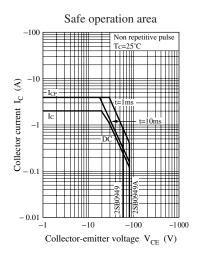


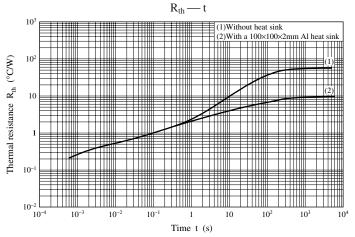












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